

# Mhh Ishak

## List of Publications by Year in descending order

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27  
papers

236  
citations

1040056

9  
h-index

996975

15  
g-index

28  
all docs

28  
docs citations

28  
times ranked

107  
citing authors

#	ARTICLE	IF	CITATIONS
1	Numerical study of the 3D Savonius turbine under stationary conditions. <i>Engineering Failure Analysis</i> , 2022, 136, 106199.	4.0	11
2	Numerical study on the influence of nozzle spray shape on spray characteristics using diesel and biofuel blends. <i>Biofuels</i> , 2021, 12, 1109-1121.	2.4	8
3	Effect of adhesive force on underfill process based on lattice Boltzmann method. <i>Microelectronics International</i> , 2020, 37, 54-63.	0.6	3
4	Effect of hourglass shape solder joints on underfill encapsulation process: numerical and experimental studies. <i>Soldering and Surface Mount Technology</i> , 2020, 32, 147-156.	1.5	7
5	Lead-free solder SAC 305 Volume Reduction and Cold Slump after Stencil Printing Process. <i>IOP Conference Series: Materials Science and Engineering</i> , 2020, 852, 012084.	0.6	0
6	Three-dimensional CFD simulation of the stencil printing performance of solder paste. <i>International Journal of Advanced Manufacturing Technology</i> , 2020, 108, 3351-3359.	3.0	7
7	Investigation of Aerodynamic Characteristics of a Wing Model With RGV Winglet. <i>Journal of Aerospace Technology and Management</i> , 2020, , .	0.3	3
8	Numerical simulation of thermal fluid-structure interaction on flexible PCB in reflow soldering atmosphere. <i>AIP Conference Proceedings</i> , 2019, , .	0.4	0
9	Comparative Study of Pressurized and Capillary Underfill Flow Using Lattice Boltzmann Method. <i>Arabian Journal for Science and Engineering</i> , 2019, 44, 7627-7652.	3.0	8
10	Optimization of 3D IC stacking chip on molded encapsulation process: a response surface methodology approach. <i>International Journal of Advanced Manufacturing Technology</i> , 2019, 103, 1139-1153.	3.0	7
11	Numerical Analysis of Nozzle Flow and Spray Characteristics from Different Nozzles Using Diesel and Biofuel Blends. <i>Energies</i> , 2019, 12, 281.	3.1	28
12	Effect of filling level and fillet profile on pin-through-hole solder joint. <i>International Journal of Advanced Manufacturing Technology</i> , 2019, 102, 1467-1485.	3.0	3
13	Effect of scale size, orientation type and dispensing method on void formation in the CUF encapsulation of BGA. <i>Sadhana - Academy Proceedings in Engineering Sciences</i> , 2018, 43, 1.	1.3	10
14	Experiential study on temperature and emission performance of micro burner during porous media combustion. <i>IOP Conference Series: Materials Science and Engineering</i> , 2018, 370, 012057.	0.6	2
15	Study on the Fluid-Structure Interaction at Different Layout of Stacked Chip in Molded Packaging. <i>Arabian Journal for Science and Engineering</i> , 2017, 42, 4743-4757.	3.0	4
16	CUF scaling effect on contact angle and threshold pressure. <i>Soldering and Surface Mount Technology</i> , 2017, 29, 173-190.	1.5	15
17	Comparative Study of the Scaling Effect on Pressure Profiles in Capillary Underfill Process. <i>IOP Conference Series: Materials Science and Engineering</i> , 2017, 203, 012012.	0.6	2
18	Scaling Effect on Velocity Profiles in Capillary Underfill Flow. <i>IOP Conference Series: Materials Science and Engineering</i> , 2017, 203, 012013.	0.6	1

#	ARTICLE	IF	CITATIONS
19	Lattice Boltzmann Model of 3D Multiphase Flow in Artery Bifurcation Aneurysm Problem. Computational and Mathematical Methods in Medicine, 2016, 2016, 1-17.	1.3	8
20	Effect of thermocapillary action in the underfill encapsulation of multi-stack ball grid array. Microelectronics Reliability, 2016, 66, 143-160.	1.7	22
21	Effect of ILU dispensing types for different solder bump arrangements on CUF encapsulation process. Microelectron Engineering, 2016, 163, 83-97.	2.4	26
22	Lattice Boltzmann method study of effect three dimensional stacking-chip package layout on micro-void formation during encapsulation process. Microelectronics Reliability, 2016, 65, 205-216.	1.7	15
23	Lattice-Boltzmann analysis of pressurized underfill process for I-type dispensing method. AIP Conference Proceedings, 2016, , .	0.4	0
24	FVM based simulation on multi-stack ball grid array (BGA). AIP Conference Proceedings, 2016, , .	0.4	0
25	Lattice Boltzmann method study of bga bump arrangements on void formation. Microelectronics Reliability, 2016, 56, 170-181.	1.7	29
26	Lattice Boltzmann Method of Different BGA Orientations on I-Type Dispensing Method. PLoS ONE, 2016, 11, e0159357.	2.5	14
27	Effect of relative humidity and wind on the human sneezing to prevent virus transmission: A numerical approach. Aerosol Science and Technology, 0, , 1-15.	3.1	3